

Part Numbers:		MMBD4448HAQW-7-F MMBD4448HADW-7-F SDA006-7		p = package designator See Data Sheet				
Weight (mg):		6.3843						
Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	3.98	0.254	1000000	39785
Leadframe	Alloy 42	Fe	7439-89-6	57.65%	30.76	1.9641	576500	177358
		Ni	7440-02-0	41.00%			410000	126135
		Mn	7439-96-5	0.60%			6000	1846
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	308
		Co	7440-48-4	0.50%			5000	1538
		Si	7440-21-3	0.15%			1500	461
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	0.95	0.0606	1000000	9492
Bond Wire	Copper Wire	Cu	7440-50-8	100.00%	0.29	0.0182	1000000	2851
Encapsulation	KTMC-1050G	SiO2	60676-86-0	69.00%	57.81	3.6909	690000	398904
		Epoxy Resin	29690-82-2	14.00%			140000	80937
		Phenol Resin	9003-35-4	7.00%			70000	40468
		Mg(OH)2	1309-42-8	8.00%			80000	46250
		C	1333-86-4	0.20%			2000	1156
		others	----	1.80%			18000	10406
		Lead Plating Finish	Matte Tin	Tin			7440-31-5	100.00%
				Total	100.00	6.3843		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, Material Composition Declaration for Electronic Products.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

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|---|--|
| Asbestos | Organic tin compounds |
| Antimony Compounds | Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.) |
| Azo compounds | Ozone Depleting Substances - Class II (HCFCs) |
| Cadmium and cadmium compounds | Perfluorooctane Sulphonate (PFOS) or related compounds |
| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE |
| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Dimethyl fumarate | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Halogens (Bromine, Chlorine, Fluorine, Iodine and Astatine) | Radioactive Substances |
| Hexavalent chromium compounds | Red Phosphorous |
| Lead and lead compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Mercury and mercury compounds | Tributyl Tin Oxide (TBTO) |

REACH SVHCs: